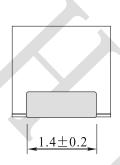
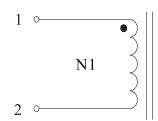
1.PHYSICAL CHARACTERISTICS(mm)

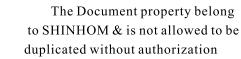
	_	2.5 ± 0.2	
			4
<u> </u>			
0.2			
1.8±0.2			
		0.4±0.2	2





2.ELECTRONICAL SCHEMATIC





Rev.	Description	Date
A0	New release	2022.12.05

3.ELECTRONICAL SPECIFICATIONS

L: $100uH \pm 5\%@0.796MHz, 0.2V$

DCR: 21Ω Max

Q: 15 Min@0.796MHz

SRF: 12MHz Min

IDC: 60mA(Inductance drop 15% Max)

Operating temperature: -40° C to $+125^{\circ}$ C(Including temp. rise)

Storage temperature: -40°C to $+105^{\circ}\text{C}$

Test Instrument:

L: HP4284A

RDC: HM2540

Note:

1. Solderability: leads shall meet MIL-STD-202,

Method 208D for solderability.

2.Flammability: UL94V-0

3.ASTM oxygen index: >28%

NAME:	E: Surface mount wound molded chip ind								
CUSTOMER P/N: NLV25T-1		01J-EF DATE:			2022-12-05				
SHINHOM P/N:	AISM1008	-101J-0.06A	REV:	A0	PAGE				
DRAWN BY		CHECKED BY	APPRO BY		OVE				

